



Product/Process Change Notice - PCN 22_0216 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Conversion of mold compound from GE100 to G311E

Publication Date: 07-Sep-2022

Effectivity Date: 10-Dec-2022 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change:

Change of mold compound from GE100 to G311E.

Reason For Change:

For better mold underfill. G311E has finer filler size compared to GE100.

Impact of the change (positive or negative) on fit, form, function & reliability:

Positive impact to reliability.

Product Identification *(this section will describe how to identify the changed material)*

This is through date code in product marking. Change will take effect starting WW49 onwards.

Summary of Supporting Information:

Test correlation and validation has been performed per ADI's standard product site to site and/or platform change correlation procedure. See attached Qualification Report.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_22_0216_Rev_-_LTM8071-G311_PCN.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com	Europe: PCN_Europe@analog.com	Japan: PCN_Japan@analog.com	Rest of Asia: PCN_ROA@analog.com
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Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (3)

LTM8071 / LTM8071EY#PBF	LTM8071 / LTM8071IY	LTM8071 / LTM8071IY#PBF		
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Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	07-Sep-2022	10-Dec-2022	Initial Release

Analog Devices, Inc.

DocId:9010 Parent DocId:None Layout Rev:8

Qualification Results Summary LTM8071 - G311

Test	Specification	Conditions	Sample Size (lots x samples)	Results
High Temperature Operating Life (HTOL)	JEDEC JESD22-A108	1000h, T _j = 125C	1 x 77	Pass
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	1000h, 150C	1 x 77	Pass
ESD, FICDM	ESDA/JEDEC JS-002	1250V	3 / Voltage	Pass
ESD, HBM	JESD22-A114	4000V	3 / Voltage	Pass
Temperature Cycle (TC)*	JEDEC JESD22-A104	1000cyc, -55C/+125C	1 x 77	Pass
Temperature Cycle (TC)*	JEDEC JESD22-A104	1000cyc, -65C/+150C	1 x 77	Pass
Thermal Shock (TS)*	JEDEC JESD22-A106	1000cyc, -55C/+125C	1 x 77	Pass
Thermal Shock (TS)*	JEDEC JESD22-A106	1000cyc, -65C/+150C	1 x 77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC JESD22-A110	264h, 110C/85%RH w/ Bias	1 x 30	Pass
Unbiased Highly Accelerated Stress Test (UHAST)*	JEDEC JESD22-A110	264h, 110C/85%RH	1 x 77	Pass

* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 48 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.